**UH Package**

32-Lead Plastic QFN (5mm × 5mm)

(Reference LTC DWG # 05-08-1693 Rev D)

**NOTE:**
1. DRAWING PROPOSED TO BE A JEDEC PACKAGE OUTLINE
   MD-220 VARIATION WHHD-(X) (TO BE APPROVED)
2. DRAWING NOT TO SCALE
3. ALL DIMENSIONS ARE IN MILLIMETERS
4. DIMENSIONS OF EXPOSED PAD ON BOTTOM OF PACKAGE DO NOT INCLUDE MOLD FLASH. MOLD FLASH, IF PRESENT, SHALL NOT EXCEED 0.20mm ON ANY SIDE
5. EXPOSED PAD SHALL BE SOLDER PLATED
6. SHADED AREA IS ONLY A REFERENCE FOR PIN 1 LOCATION
   ON THE TOP AND BOTTOM OF PACKAGE

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**PACKAGE OUTLINE**

- **PIN 1 TOP MARK**
- **(NOTE 6)**
- **RECOMMENDED SOLDER PAD LAYOUT**
  - APPLY SOLDER MASK TO AREAS THAT ARE NOT SOLDERED
- **BOTTOM VIEW—EXPOSED PAD**
  - **PIN 1 NOTCH R = 0.30 TYP / OR 0.35 × 45° CHAMFER**

**APPLY SOLDER MASK TO AREAS THAT ARE NOT SOLDERED**